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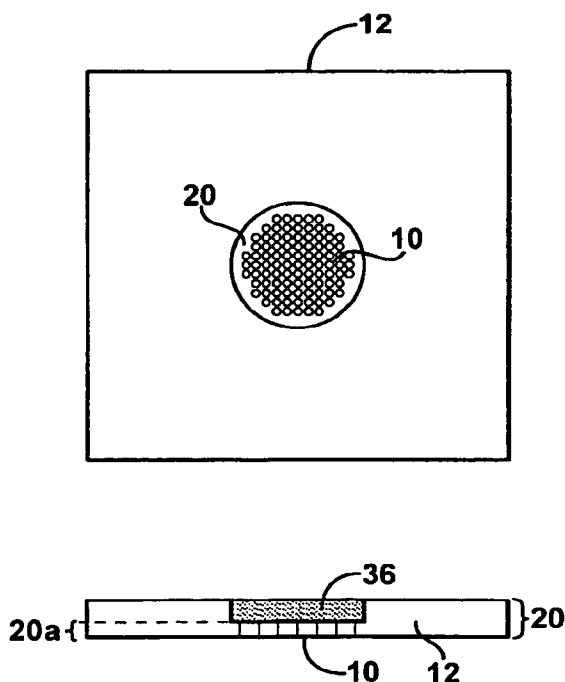
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(54) Title: PROCESS FOR STRUCTURALLY THINNING MATERIALS DRILLED WITH VIA PATTERNS

(57) Abstract: A method for thinning a substrate prior to drilling and/or for structurally reinforcing a thinned substrate having a via pattern after drilling and products resulting thereby. A substrate, or panel, has a first thickness. A pocket is formed in the substrate where the pocket has a second thickness less than the first thickness. At least one via is drilled in the pocket, and the via(s) are filled with an optically transmissive material.





PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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